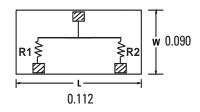
THIN FILM SURFACE MOUNT RESISTORS

RSMT-23 (23:) Direct Replacement for SOT-23





MINI-SMT™ RSMT-23 SERIES RESISTOR

MINI-SMT-23TM thin film resistors offer maximum benefits in ohmic value ranges from 1Ω through 500M Ω . T.C.R.'s to ±5ppm/°C - and absolute tolerances to 0.05%. These packaged resistors provide proven thin film performance in a surface mount solderable style.

MECHANICAL DATA

SIZE: RSMT(23) 0.112" x 0.090" (±0.005") x 0.050"MAX NOM.

SUBSTRATE ALUMINA RESISTOR **PROPRIETARY**

GOLD OR SOLDER, PALLADIUM SILVER OPTIONAL BONDING MATERIAL

BOND PAD SIZE (23) 0.018" x 0.020" ±0.003"

ELECTRICAL DATA

RESISTANCE RANGE 1Ω TO $500M\Omega$ **TOLERANCES** 0.1%, 0.5%, 1%, 2%, 5%, 10%: TO 0.05% AVAILABLE

T.C.R.

 $1\Omega T0 50M\Omega$ ±150ppm/°C STANDARD: OPTIONAL TO ±5ppm/°C $50M\Omega$ TO $500M\Omega$ ±300ppm/°C STANDARD: OPTIONAL TO ±100ppm/°C

SERIES DATA

CURRENT NOISE 101Ω TO 250KΩ: -40dB

 \leq 100 Ω , \geq 250K Ω : -30dB

DIELECTRIC BREAKDOWN 400 V MIN. **INSULATION RESISTANCE** 10¹²Ω MIN. OPERATING VOLTAGE 100 V MAX.

POWER RATING 250 mW (70°C DERATED LINEARLY TO 150°C) P = E2/R **SHORT TERM OVERLOAD** 5X RATED POWER, 25°C, 5 SEC., ±0.25% MAX. \(\Delta R/R: \pm 0.1% MSI TYPICAL \)

HIGH TEMP EXPOSURE 150°C, 100 HRS., ±0.25% MAX. △R/R: ±0.03% MSI TYPICAL

THERMAL SHOCK MIL-STD 202, METHOD 107F, ±0.25% MAX. ΔR/R: ±0.1% MSI TYPICAL **MOISTURE RESISTANCE** MIL-STD 202, METHOD 106, ±0.5% MAX. Δ R/R: ±0.1% MSI TYPICAL **STABILITY** 1000 HRS., 70°C, 125mW, ±0.5% MAX. △R/R: ±0.1% MSI TYPICAL

 $RE = \pm 0.25\%RATIO$ $RD = \pm 0.5\% RATIO$

-55°C TO +150°C

PART NUMBER DESIGNATION

OPERATING TEMP RANGE

RSMT 23	A	P	_ XXXXX/XXXXX	X	– <u>X</u>
SERIES	SUBSTRATE	RESISTIVE FILM	OHMIC VALUE R1 / R2	TOLERANCE Q = 0.05%**	OPTION Designator
(23): 0.112x 0.090x0.050	A = Alumina	P = Proprietary	5-Digit Number: 1st 4 Digits Are Significant With "R" As Decimal Point When Required. 5th Digit Represents Number of Zeros.	B = 0.1%** D = 0.5% F = 1% G = 2% J = 5% K = 10%	(If Required) A = ±50ppm/°C B = ±25ppm/°C** C = ±10ppm/°C** D = ±5ppm/°C** F = ±100ppm/°C T = Solder Terminations T3 = Leadfree Solder Terminations U = Untinned TR = Tape & Reel* PS = Pd Silver Bond Pads G = Gold Bond Pads RA = ±0.01% RATIO RB = ±0.05% RATIO RC = ±0.1% RATIO

EXAMPLES: RSMT 23 AP-50003B-CT = 0505, $5M\Omega$, $\pm 0.1\%$ Tol., ± 10 ppm/°C with Solder Termination.

*CONSULT SALES FOR AVAILABILITY **VALUE DEPENDENT

